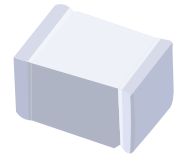
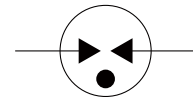


FEATURES

- | Surface Mounting Design 3.2*1.6*1.6mm
- | High Current Handling Capability 500A @ 8/20 μ s
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



3.2*1.6*1.6mm




Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	140-260	V
Impulse Spark-over Voltage	At 1kV/ μ s	for 99 % of measured values \leq 950	V
	At 1kV/ μ s	Typical values of distribution \leq 900	V
Impulse Discharge Current 2)	8/20 μ s	500	A
Insulation Resistance	DC=100V	\geq 1	G Ω
Capacitance at 1MHz	V _{DC} =0.5V	\leq 0.6	pF
Operating And Storage Temperature		-40-125	$^{\circ}$ C

1) In ionized mode

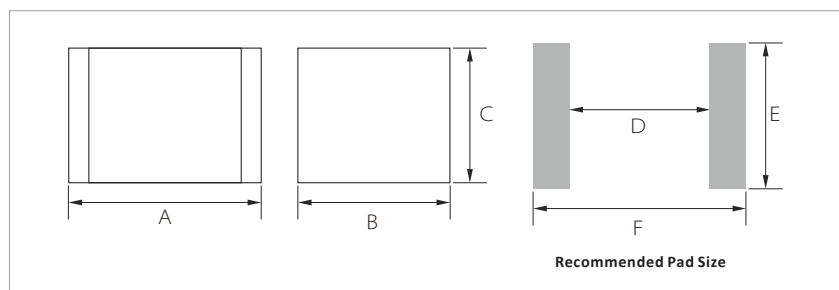
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min
Resistance of soldering heat	Temperature:260 $^{\circ}$ C; Time of dip soldering :10s,1time

NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

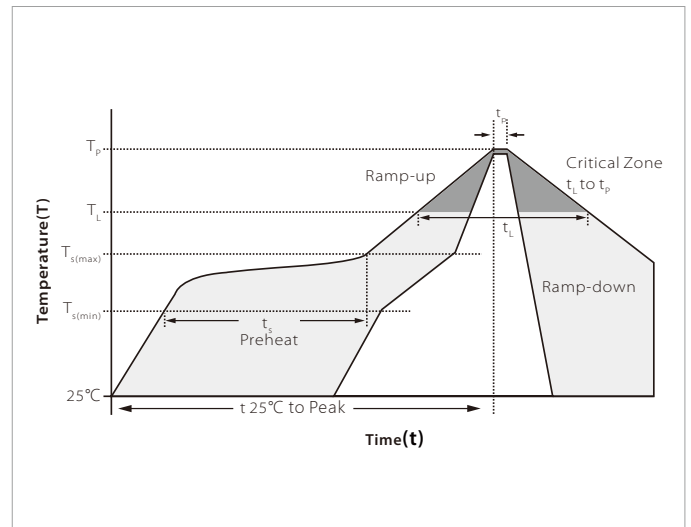
PRODUCT DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref	mm
A	3.2 \pm 0.3mm
B	1.6 \pm 0.3mm
C	1.6 \pm 0.3mm
D	2.0mm
E	1.8mm
F	3.7mm

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T_L) to peak		3°C/second max
$T_s(\text{max})$ to T_L - Ramp-up Rate		
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG3216B200	3.2*1.6*1.6mm	2000PCS	7"

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By QR Code

Website



Wechat

To find your local partner within Semiware's global network: www.semiware.com

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